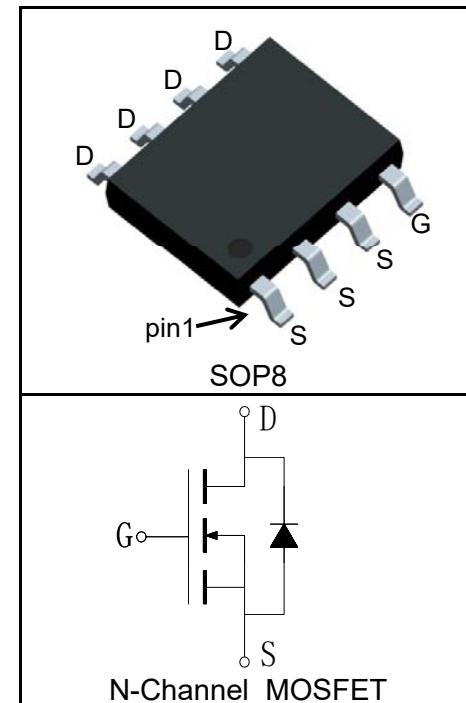


Features

- 20V/16A,
- $R_{DS\ (ON)} = 3.5\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 10\text{V}$
- $R_{DS\ (ON)} = 4\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 4.5\text{V}$
- $R_{DS\ (ON)} = 5\text{m}\Omega\ (\text{Typ.}) @ V_{GS} = 2.5\text{V}$
- Low $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

Pin Description



Applications

- Power Management
- Battery Protection



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_S	Diode Continuous Forward Current	$T_A = 25^\circ\text{C}$	A
Mounted on Large Heat Sink			
$I_{DP}^{(1)}$	300 μs Pulse Drain Current Tested	$T_A = 25^\circ\text{C}$	64
$I_D^{(2)}$	Continuous Drain Current ($V_{GS} = 4.5\text{V}$)	$T_A = 25^\circ\text{C}$	16
		$T_A = 70^\circ\text{C}$	12.8
P_D	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	2.5
		$T_A = 70^\circ\text{C}$	1.6
$R_{\theta JC}$	Thermal Resistance-Junction to Case	-	$^\circ\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	50	$^\circ\text{C/W}$
Drain-Source Avalanche Ratings			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	64	mJ

Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KS2211HB			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V			1	μA
		T _J =125°C			30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.4	0.7	1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
R _{DS(ON)} ^⑤	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =10A		3.5	5	mΩ
		V _{GS} =4.5V, I _{DS} =8A		4	6	mΩ
		V _{GS} =2.5V, I _{DS} =4A		5	8	mΩ
Diode Characteristics						
V _{SD} ^⑤	Diode Forward Voltage	I _{SD} =10A, V _{GS} =0V		0.82	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =10A, dI _{SD} /dt=100A/μs		18		ns
Q _{rr}	Reverse Recovery Charge			35		nC
Dynamic Characteristics ^⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.8		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, Frequency=1.0MHz		2525		pF
C _{oss}	Output Capacitance			395		
C _{rss}	Reverse Transfer Capacitance			380		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V, I _{DS} =10A, V _{GEN} =4.5V, R _G =3Ω		7		ns
t _r	Turn-on Rise Time			10		
t _{d(OFF)}	Turn-off Delay Time			31		
t _f	Turn-off Fall Time			15		
Gate Charge Characteristics ^⑥						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _{DS} =10A		25		nC
Q _{gs}	Gate-Source Charge			8		
Q _{gd}	Gate-Drain Charge			10		

Notes: ①Pulse width limited by safe operating area.

②Calculated continuous current based on maximum allowable junction temperature.

③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.

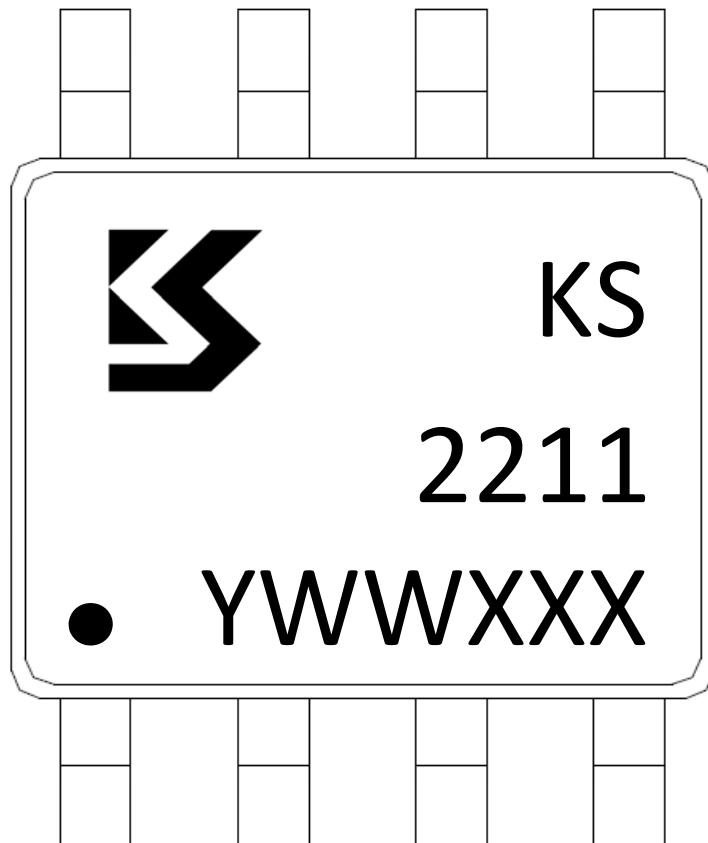
④Limited by T_{Jmax}, starting T_J = 25°C, L = 0.1mH, R_G = 25Ω, I_{AS} = 36A, V_{GS} = 10V.

⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.

⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS2211HB	SOP8	Tape&Reel	3000	13"	12mm

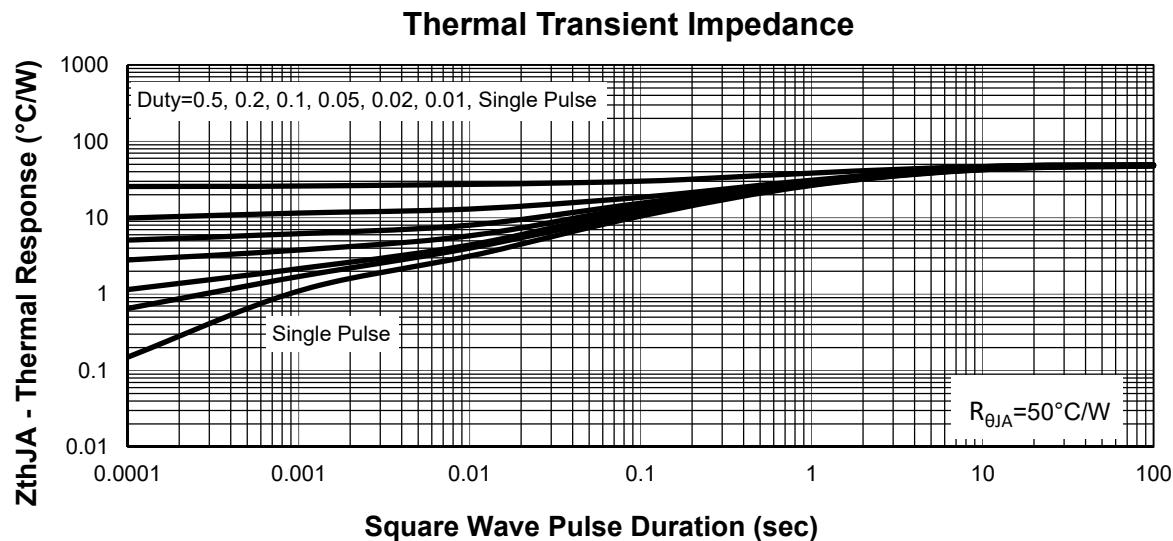
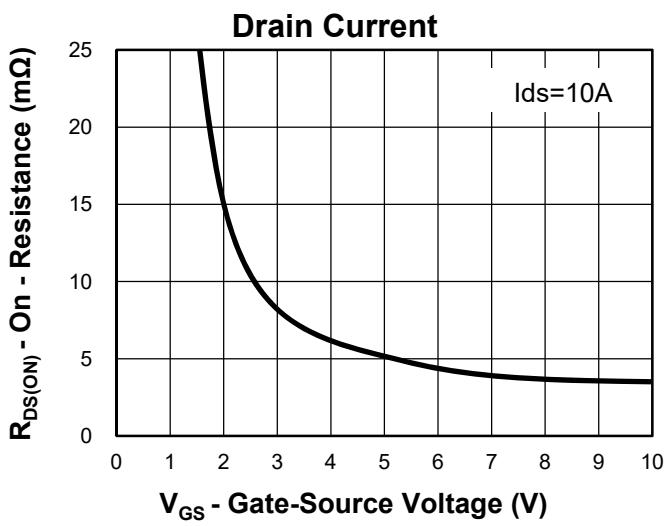
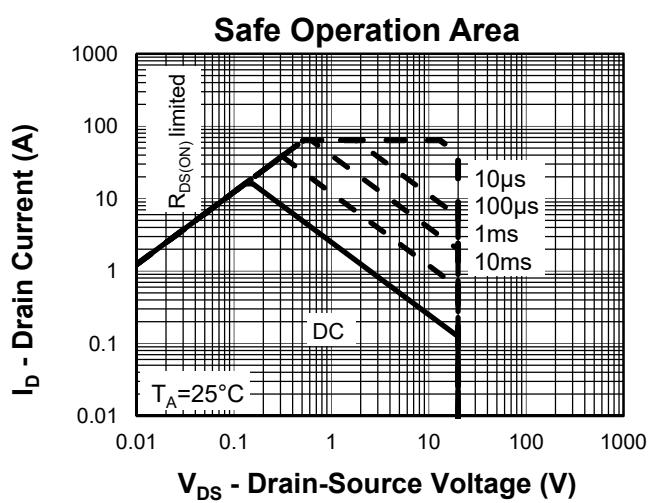
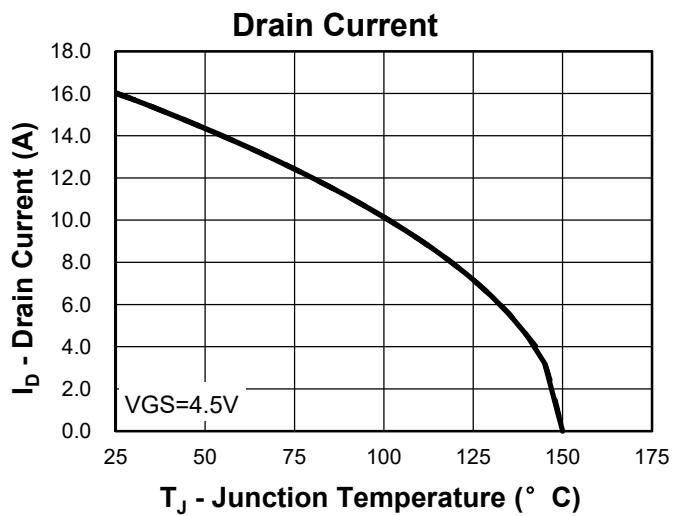
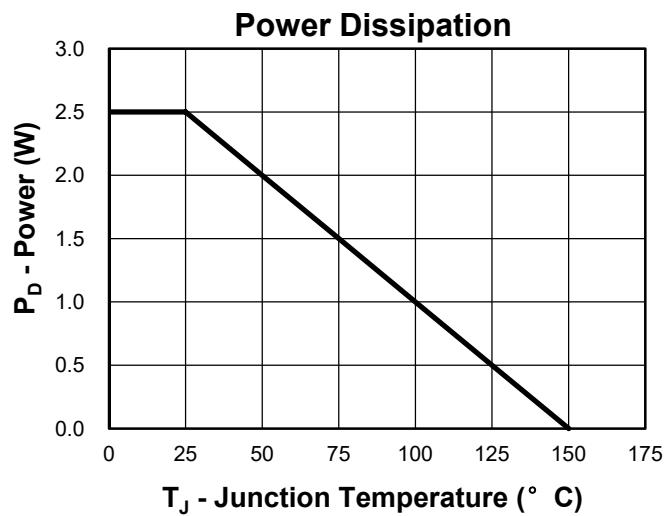


Y =Year,2017-A,2018-B,etc.

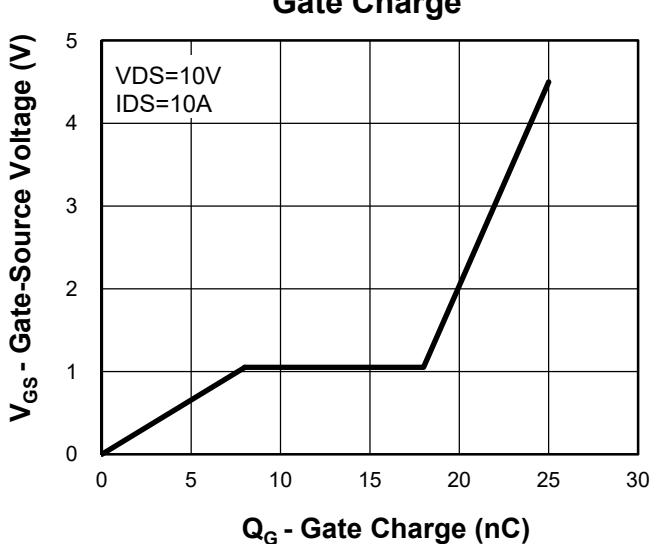
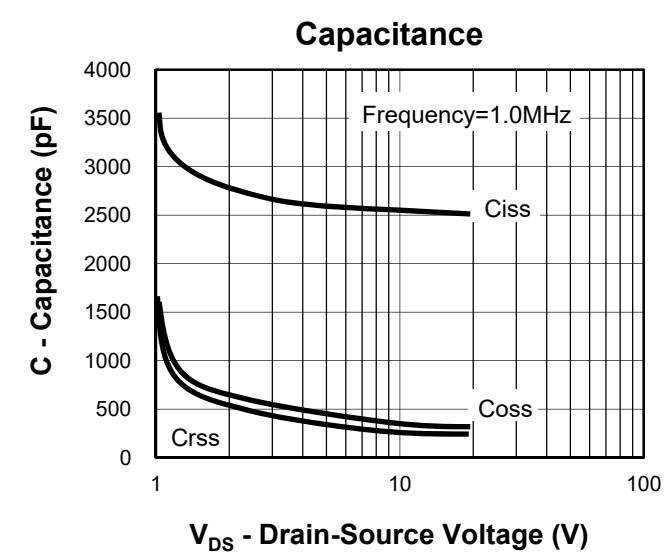
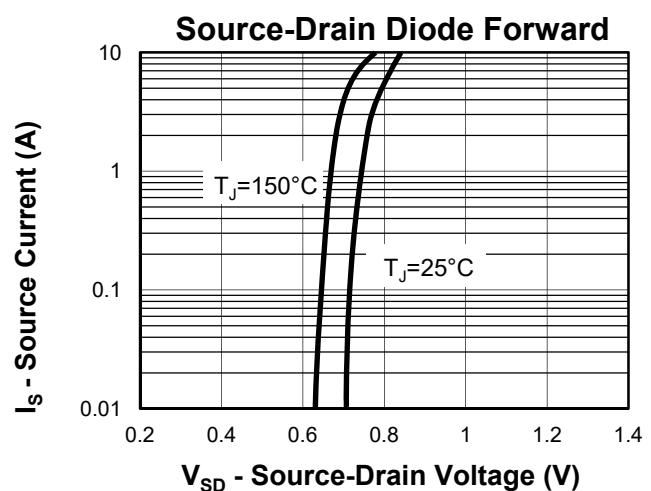
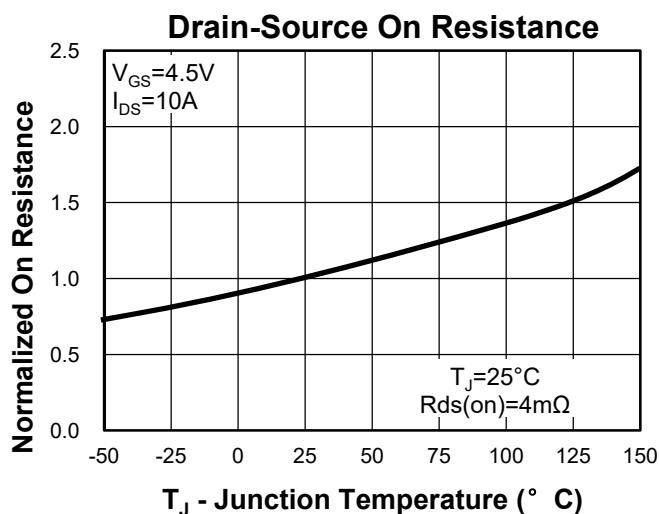
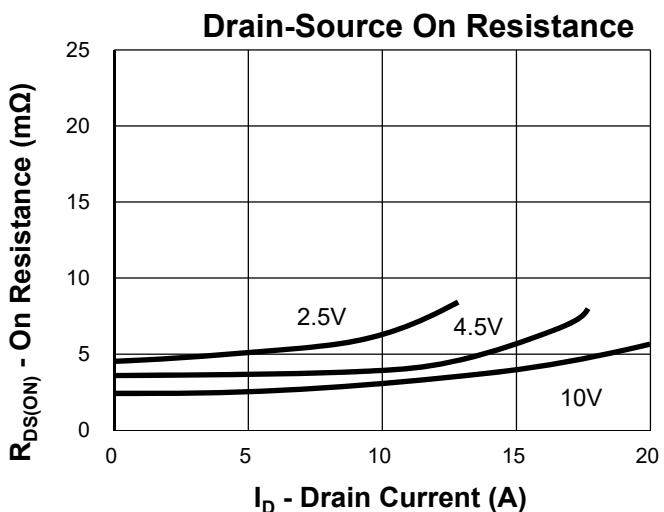
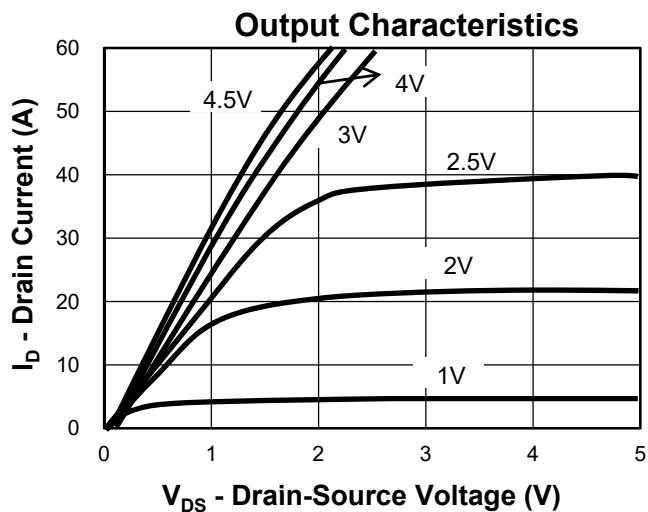
WW =Week.

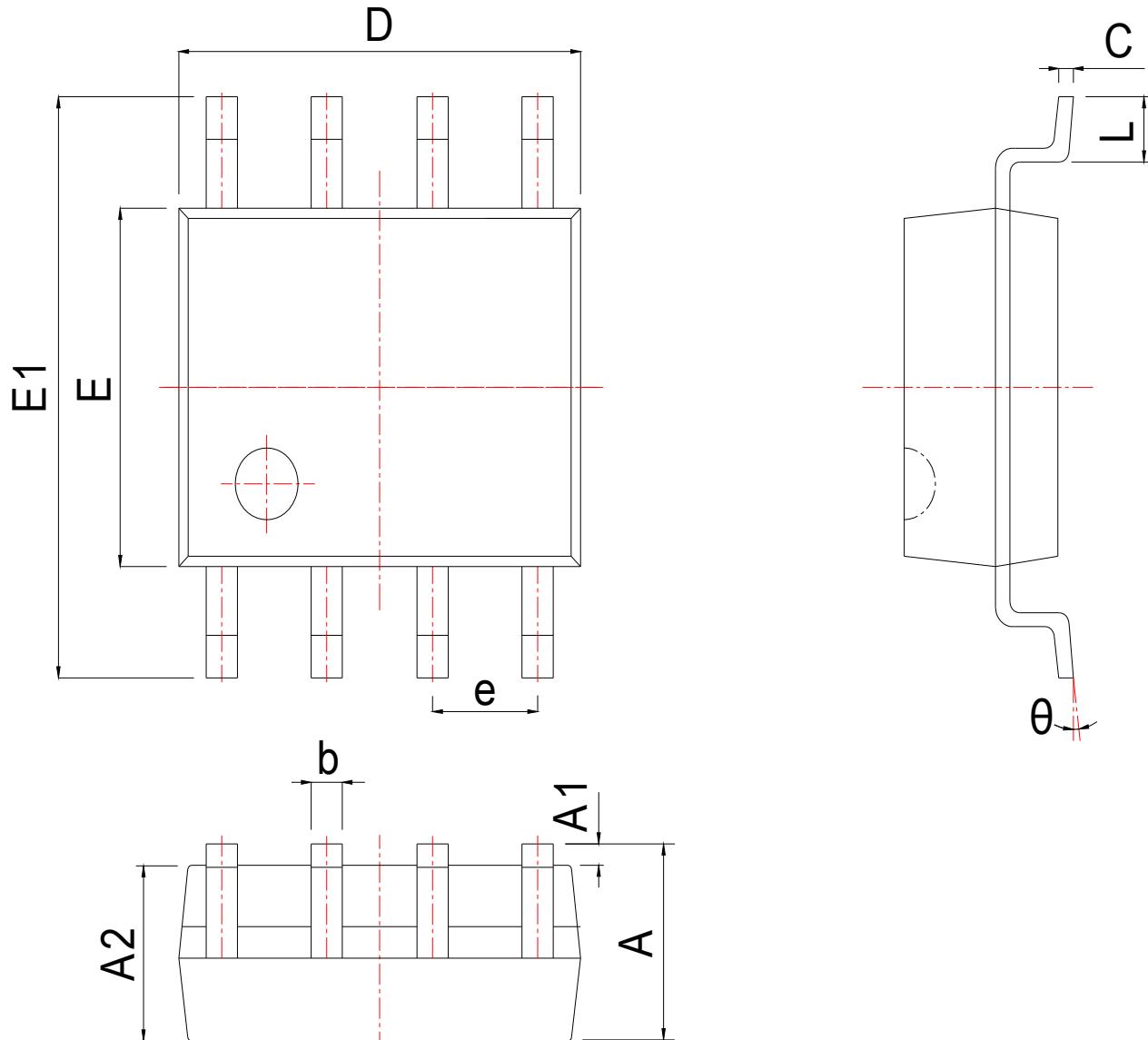
XXX =Lot number.

Typical Characteristics



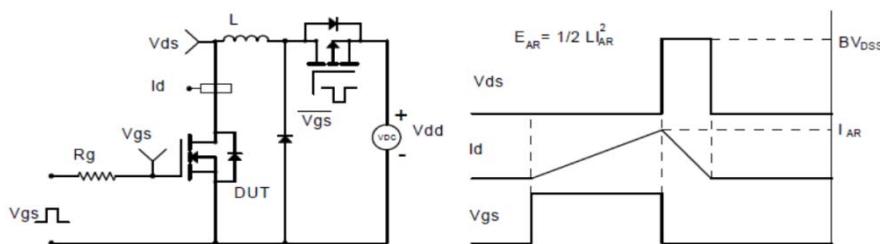
Typical Characteristics



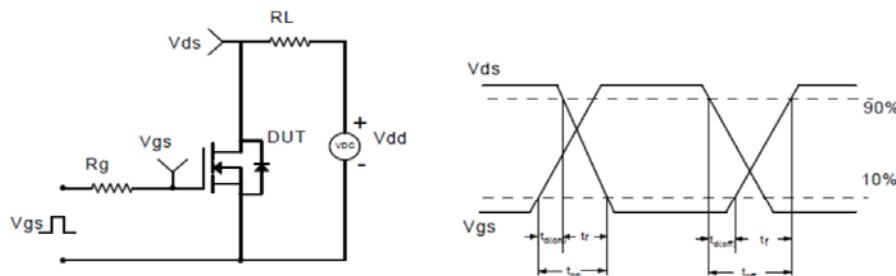
Package Information
SOP8


SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.300	1.525	1.750	0.051	0.060	0.069
A1	0.050	0.150	0.250	0.002	0.006	0.010
A2	1.350	1.450	1.550	0.053	0.057	0.061
b	0.330	0.420	0.510	0.013	0.017	0.020
c	0.170	0.210	0.250	0.007	0.008	0.010
D	4.700	4.900	5.100	0.185	0.193	0.201
E	3.800	3.900	4.000	0.150	0.154	0.157
E1	5.800	6.000	6.200	0.228	0.236	0.244
e	1.270 BSC			0.050 BSC		
L	0.400	0.835	1.270	0.016	0.033	0.050
θ	0°		8°	0°		8°

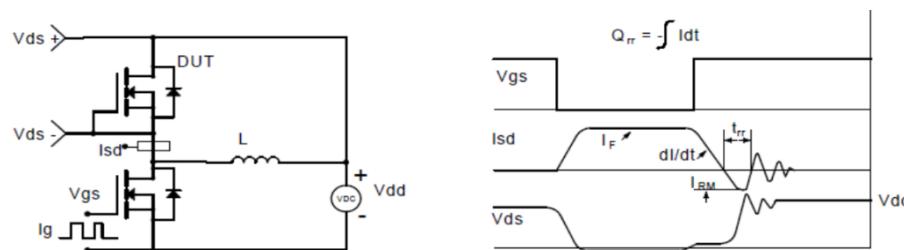
Avalanche Test Circuit and Waveforms



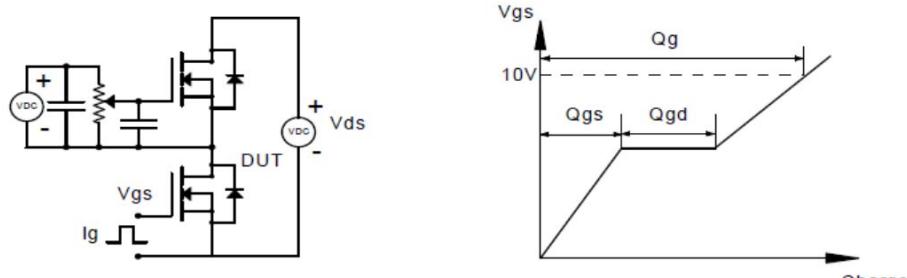
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

Kwansemi Semiconductor Co.,Ltd

Email:Sales@kwansemi.com

Web:www.kwansemi.com

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